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REMARKS/ARGUMENTS

Claims 15-25 are pending in this application. By this Amendment, Applicants cancel claims 1-14 and amend claim 15.

Applicants have canceled claims 1-14 since these claims are directed to a non-elected invention. Applicants reserve the right to file a Divisional Application to pursue prosecution of non-elected claims 1-14.

Claims 15, 17 and 22-25 were rejected under 35 U.S.C. § 102(b) as being anticipated by Ooyama et al. (U.S. 6,191,494). Claims 15 and 17 were rejected under 35 U.S.C. § 102(e) as being anticipated by Awad et al. (U.S. 6,894,382). Claim 18 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Ooyama et al. in view of Lau et al. (U.S. 6,667,073). Claims 19-21 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Ooyama et al. in view of Lee et al. (U.S. 6,661,083). Claims 16 and 21 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Ooyama et al. in view of Lee et al., and further in view of Yoneda et al. (U.S. 6,376,921). Applicants respectfully traverse the rejections of claims 15-25.

Claim 15 has been amended to recite:

“A leadless plastic chip carrier comprising:
a die attach pad;
at least one semiconductor die mounted on said die attach pad;
a plurality of contact pads circumscribing and offset from said die attach pad;
a plurality of wire bonds connecting said at least one semiconductor die and various ones of said contact pads; and
an overmold covering said semiconductor die and all except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude.”
(emphasis added)

With the unique combination and arrangement of features recited in Applicants' claim 15, including the features of “an overmold covering said semiconductor die and all

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except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude," Applicants have been able to provide a simple, low-cost leadless plastic chip carrier in which the length of wire bonds are reduced so as to reduce the electrical impedance thereof to enable operation at higher frequencies (see, for example, paragraph [009] on page 4 of the originally filed specification).

The Examiner alleged that each of Ooyama et al. and Awad et al. teaches all of the features recited in Applicants' claim 15.

Claim 15 has been amended to recite the features of "an overmold covering said semiconductor die and all except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude."

In contrast to Applicants' claim 15, Figs. 4A and 6 of Ooyama et al. clearly teach contact pads 26, 26' which have all but one surface exposed from the molding compound 23, and which protrude from the molding compound 23 so as to be disposed in a common plane with the die attach pad 28. Thus, Ooyama et al. certainly fails to teach or suggest the features of "an overmold **covering** said semiconductor die and **all except one surface of each of said contact pads** such that **said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude**" as recited in Applicants' claim 15.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 15 under 35 U.S.C. § 102(b) as being anticipated by Ooyama et al.

Similar to Ooyama et al., Fig. 4A of Awad et al. teaches contact pads 230 which include sections 232 and 234, wherein a plurality of surfaces of the contact pads are exposed from the overmold, and sections 232 of the contact pads 230 protrude from the overmold so as to be disposed in a common plane with the die attach pad 17. Thus, Awad et al. certainly fails to teach or suggest the features of "an overmold **covering**

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said semiconductor die and all **except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude**" as recited in Applicants' claim 15.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 15 under 35 U.S.C. § 102(e) as being anticipated by Awad et al.

The Examiner relied upon Lau et al., Lee et al. and Yoneda et al. to allegedly cure various deficiencies of Ooyama et al. However, none of Lau et al., Lee et al. and Yoneda et al. teaches or suggests the features of "an overmold covering said semiconductor die and all except one surface of each of said contact pads such that said overmold substantially lies in a plane from which said die attach pad protrudes and from which said contact pads do not protrude" as recited in Applicants' claim 15. Thus, Applicants respectfully submit that Lau et al., Lee et al. and Yoneda et al. fail to cure the deficiencies of Ooyama et al. described above.

Accordingly, Applicants respectfully submit that Ooyama et al., Awad et al., Lau et al., Lee et al. and Yoneda et al., applied alone or in combination, fail to teach or suggest the unique combination and arrangement of elements recited in Applicants' claim 15.

In view of the foregoing amendments and remarks, Applicants respectfully submit that Claim 15 is allowable. Claims 16-25 depend upon claim 15, and are therefore allowable for at least the reasons that claim 15 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

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The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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Attorneys for Applicant

Joseph R. Keating
Registration No. 37,368

Christopher A. Bennett
Registration No. 46,710

KEATING & BENNETT LLP
8180 Greensboro Drive, Suite 850
Tyson's Corner, VA 22102
Telephone: (703) 637-1480
Facsimile: (703) 637-1499